



Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Idea for printed circuit board
- Glass passivated Junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed
250°C/10 seconds at terminals

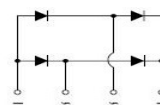
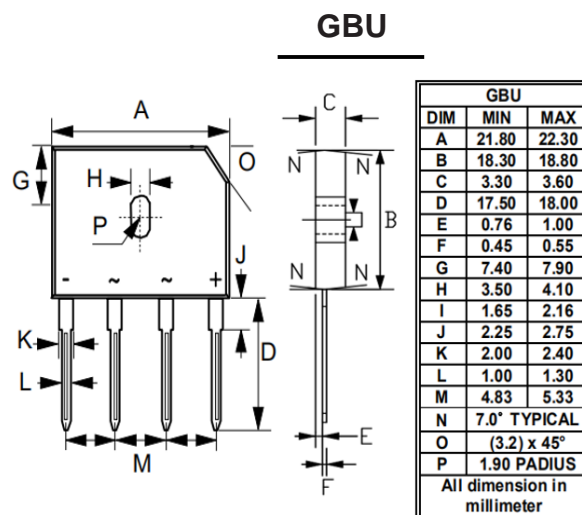
Mechanical Data

Case : Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750,Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any



Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	EGBU 606	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	600	V
Maximum RMS voltage	V_{RMS}	420	V
Maximum DC blocking voltage	V_{DC}	600	V
Maximum average forward rectified current with heatsink	$I_{(AV)}$	6.0	A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	175.0	A
Rating for fusing (t=8.3ms, Ta=25°C)	I_t^2	127.1	A ² _s
Maximum instantaneous forward voltage at 6.0A	V_F	1.7	V
Maximum DC reverse current T _A =25°C at rated DC blocking voltage T _A =125°C	I_R	5.0 500	uA
Maximum reverse recovery time (Note 4)	T_{rr}	40	ns
Typical thermal resistance	R_{qJA}	31.0	°C/W
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150	°C

Note:

- 1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
- 2.Mounted on glass epoxy PC board with 1.3mm² solder pad.
- 3.Device mounted on 50mm x 50mm x 1.6mm Cu Plate Heatsink.
- 4.Reverse Recovery Test Conditions:IF=0.5A,IR=1.0A,IRR=0.25A.



Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

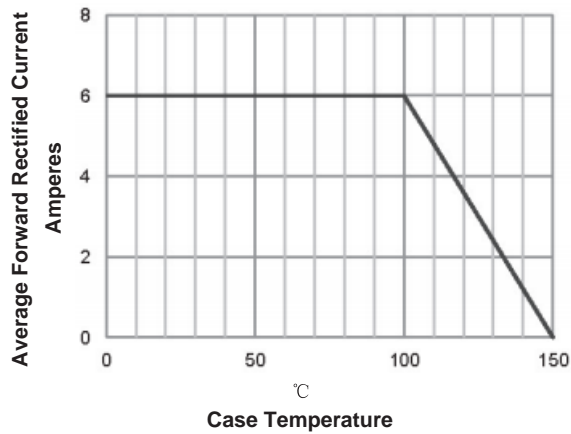


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

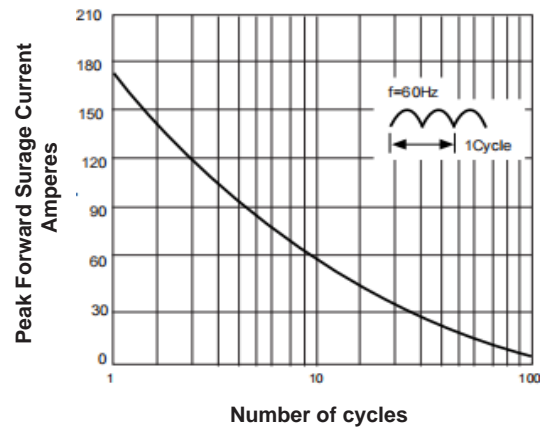


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

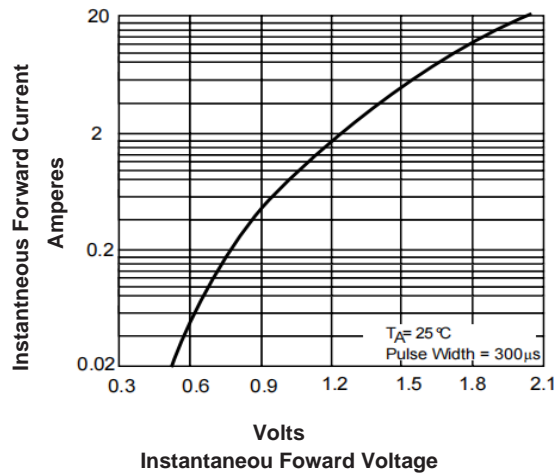


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

